

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re application of:

TONGBI JIANG  
EDWARD SCHROCK

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

Examiner: PAREKH, N.

Title: BGA PACKAGE HAVING SUBSTRATE  
WITH PATTERNED SOLDER MASK  
DEFINING OPEN DIE ATTACH AREA  
(AS AMENDED)

Attorney Docket No.: 98-0645.1

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16/D  
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8-7-01

**AMENDMENT**

**July 23, 2001**

Assistant Commissioner for Patents  
BOX AMENDMENT (FEE)  
Washington, D.C. 20231

Sir:

This Amendment is in response to the Office Action dated March 21, 2001 having a statutory period for response set to expire on June 21, 2001, but extended for 30 days until July 23, 2001 by the enclosed Petition for Extension of Time. Please amend the captioned case as follows.

**In the Specification:**

Please delete page 11, lines 15-20, and substitute the following clean replacement paragraph. In addition, a marked version of the specification showing the changes follows the Remarks section.

--As also shown in Figure 3C, exposing and developing the mask material 74B forms the solder mask 80B on the second surface 46 of the substrate 56. The solder mask 80B includes a die attach opening 86 having an outline corresponding to but only slightly larger than the outline of the semiconductor die 16.--

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